## IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A display apparatus, comprising:

an insulating substrate;

a signal line for transmitting a signal to a pixel formed in a display area composed of pixels on the insulating substrate;

a driver integrated circuit (IC) mounted outside of the display area of the insulating substrate and electrically connected to the signal line; and

an inspection pad formed outside of the display area of the insulating substrate, electrically connected to the signal line, and covered with resin;

a wiring substrate for inputting a signal from outside of the insulating substrate to the driver IC,

wherein the wiring substrate and the signal input pad are electrically connected by an anisotropic conductive film, and

the wiring substrate covers the signal input pad and has a portion above the inspection pad that is cut away.

Claim 2 (Original): A display apparatus according to Claim 1, wherein the resin is selected from the group consisting of silicon, acryl, urethane, epoxy, and polyimide.

Claim 3 (Currently Amended): A display apparatus according to Claim 1, wherein the resin is an the anisotropic conductive film.

Claim 4 (Currently Amended): A display apparatus according to Claim 1, further comprising:

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an insulating substrate;

a signal line for transmitting a signal to a pixel formed in a display area composed of pixels on the insulating substrate;

a driver integrated circuit (IC) mounted outside of the display area of the insulating substrate and electrically connected to the signal line; and

an inspection pad formed outside of the display area of the insulating substrate, electrically connected to the signal line, and covered with resin;

a signal input pad formed outside of the display area of the insulating substrate, for inputting a signal from outside of the insulating substrate to the driver IC[[,]]: and

an IC signal pad formed at a position corresponding to the driver IC on the insulating substrate, and formed to connect the signal line and driver IC.

wherein the signal input pad, the IC signal pad and the inspection pad are covered with an anisotropic conductive film.

Claim 5 (Original): A display apparatus according to Claim 1, further comprising: a conductive extension line connecting the signal line and the driver IC to the inspection pad.

Claim 6 (Original): A display apparatus according to Claim 2, further comprising: a conductive extension line connecting the signal line and the driver IC to the inspection pad.

Claim 7 (Original): A display apparatus according to Claim 3, further comprising: a conductive extension line connecting the signal line and the driver IC to the inspection pad.

Claim 8 (Currently Amended): A display apparatus according to Claim 4, further comprising:

a conductive extension line connecting the <u>IC signal pad signal line and the driver IC</u> to the inspection pad.

Claim 9 (Canceled)

Claim 10 (Currently Amended): A display apparatus according to Claim [[9]] 1, wherein the wiring substrate is a flexible substrate.

Claim 11 (Original): A display apparatus according to Claim 4, wherein the inspection pad and the signal input pad are substantially aligned along near an edge of the insulating substrate.

Claim 12 (Withdrawn): A method of manufacturing a display apparatus, comprising steps of:

forming a signal line for transmitting a signal to a pixel formed in a display area on the insulating substrate;

implementing a driver integrated circuit (IC) outside of the display area of the insulating substrate and electrically connecting the driver IC to the signal line;

forming an inspection pad outside of the display area of the insulating substrate and electrically connecting the inspection pad to the signal line;

forming a signal input pad outside of the display area of the insulating substrate, for inputting a signal from outside of the insulating substrate to the driver IC; and

simultaneously covering the inspection pad and the signal input pad with an anisotropic conductive film.

Claim 13 (Withdrawn): A method of manufacturing a display apparatus, comprising steps of:

forming a signal line for transmitting a signal to a pixel formed in a display area on the insulating substrate;

implementing a driver integrated circuit (IC) outside of the display area of the insulating substrate and electrically connecting the driver IC to the signal line;

forming an IC signal pad at a position corresponding to a pad formed on the driver IC on the insulating substrate;

forming an inspection pad outside of the display area of the insulating substrate and electrically connecting the inspection pad to the signal line;

forming a signal input pad outside of the display area of the insulating substrate, for inputting a signal from outside of the insulating substrate to the driver IC; and

simultaneously covering the inspection pad and the signal input pad with an anisotropic conductive film.

Claim 14. (New) A display apparatus according to Claim 1, wherein the anisotropic conductive film is formed on the inspection pad and the anisotropic conductive film on the inspection pad is coated with the resin.

Claim 15. (New) A display apparatus according to Claim 14, wherein the resin is selected from the group consisting of silicon, acryl, urethane, epoxy, and polyimide.